

# Non-Silicone Putty Gel / XK-GN30

## Introduction

Syringes packaging, automated production, high temperature, non-corrosive to metal, 100% thermal curing putty. Non Silicone Gel is high thermal performance Gel, it based on TPR, Filled with a variety of high performance ceramic powder. It also has high thermal conductivity, low thermal resistance, good insulation characteristics.

## Features

- Good compressibility
- Non-silicone
- Non-curing
- Resists pump-out

## Applications

- Consumer electronics.
- Automotive Systems.
- Telecommunications



		XK-GN30	Method
Color		Blue	visual
Flow Rate (30cc EFD cartridges 0.100" orifice 90psi)	g/min	5	
Specific Gravity	g/cm <sup>3</sup>	3.0	ASTM D792
Volume Resistivity	Ωcm	>10 <sup>13</sup>	ASTM D257
Thermal Conductivity	W/mK	3.0	HOT DISK
Breakdown Voltage	KV/mm	10	ASTM D149
Dielectric Constant	1	8	ASTM D150
Low limit BLT Thickness	mm	0.08	ASTM D374
Application temperature	°C	-30~150	
Shelf life	month	12	
Siloxane Volatiles D4~D20	%	0	GC-FID
Coefficient of Thermal Expansion,	ppm/K	180	
Flammability	UL94	V-0	UL94